

#### Accelerating the next technology revolution

# SEMATECH Policy on EUV Resist Outgassing







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#### SEMATECH Viewpoint: Resist Outgassing



#### It's Showtime for EUVL

- We have about 2 to 3 years to enable EUVL Pilot Lines for at least two of our member companies.
- If EUVL fails to work in these pilot lines then the future is bleak for EUVL.
- > We need to concentrate on high risk items
  - Resources are limited
- For ~ five years, the industry has been testing EUVL resist outgassing levels out of concern for potential contamination of exposure tool optics.
  - Has anyone seen a problem with resist? NO
- Do we really want to transform the high risk RLS triangle for EUV resist into a pyramid that includes ultra-low outgassing requirements?

## **Discussion – Current Scanners**



- No data exists to date implicating resist outgassing in any tool optical contamination
- No data exists showing resist contamination <u>significantly</u> contributes to witness plate contamination above residual chamber organic contributions at current small-field and full-field power levels
- All tests to date indicate residual hydrocarbons are the dominant source of contamination at current power levels
- No justification has been shown for continuing resist outgas testing of any kind for small-field and current full-field low power scanners
- Significant resources are required to judge which resists should be tested, to arrange for testing, to perform the tests, and to report the results
  - SEMATECH is discontinuing resist outgas testing for our MET tools with conventional PAG resists.

## **Discussion – Future Scanners**



- Future scanners will need to improve orders of magnitude in residual organics before resist outgassing should be considered as any significant threat.
- Future scanners will have in-situ carbon cleaning techniques; the presence of such capability should be fully comprehended in any budget analysis of allowable hydrocarbons from all sources.
- If in situ cleaning is successful on future scanners, then resist outgassing is not of concern.
- Scanner suppliers need to convince customers of the need for any resist outgassing limits with careful hydrocarbon budget analysis.



### **Backup Slides**

## **Counting Molecules Approach:**

How Intel/SEMATECH Specification was Determined

MET primary mirror M2 assumed to be the optic at greatest risk from resist outgas products (only optical lens surface with a direct line-of-sight to the resist).



2003/2004 /2005 Spec	2006 – current Spec
<ul> <li>M2s 'permitted' to acquire 1 monolayer of carbon after 3 years (about <u>0.3%</u> reflectivity loss)</li> </ul>	• Same
<ul> <li>Usage: 64 fields/wafer, 30 wafers/week, 48 weeks/year, 3 years.</li> </ul>	<ul> <li>64 fields/wafer, 36 wafers/week, 40 weeks/year, 3 years.</li> </ul>
<ul> <li>Surface impingement: 100% of all outgas molecules hit M2.</li> </ul>	<ul> <li>20% of all outgas molecules hit M2.</li> </ul>
• Surface sticking probability: 100% of all molecules that hit stick to M2.	<ul> <li>85% of all molecules that hit stick to M2.</li> </ul>
<ul> <li>Molecular disassociation: Each molecule that sticks generates 10 carbon atoms.</li> </ul>	• Each molecule that sticks generates 5 carbon atoms.

≤ 6.5E+13 molecules/cm<sup>2</sup>

≤ 6.5E+14 molecules/cm<sup>2</sup>

# **SEMATECH/Intel Approach**



- Still <u>very conservative</u> assumptions in current resist outgas spec level.
- > Yet most resists tested in 2007 passed SEMATECH/Intel outgassing limit.



- 119 tested out of 224+ used on MET tools in 2007, 51 commercial shown
- Sometimes we allowed resists on MET tools even if they failed our spec.
- How have we done on protecting the MET tools?

#### **Optics Contamination on SEMATECH's MET Tool**

- SEMATECH has swapped <u>illuminator</u> mirror optics twice due to contamination
- > With each swap, total system power has been restored to  $\geq$  original value
  - Intel has experienced same response
- No sign of significant accumulation of carbon on MET primary optics.



Shots required per 1 mJ of dose as a function of accumulated dose

#### It looks like Sandia was correct in 2002; cause is residual organics